/ Descriptions Ң

SOT-23

Zener Diode in a SOT-23 Plastic Package.

/ F

300mW

300mW power dissipation, Ideally Suited for Automated Assembly. HF Product.

2.4V-51V

2.4V to 51V wide zener voltage range applications.

PIN: See Equivalent Circuit.

/ h_{FE} Classifications & Marking

See Electrical Characteristics.

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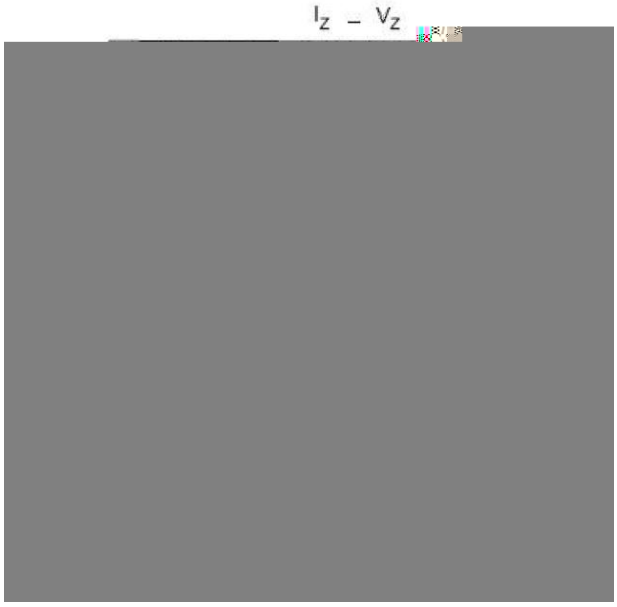
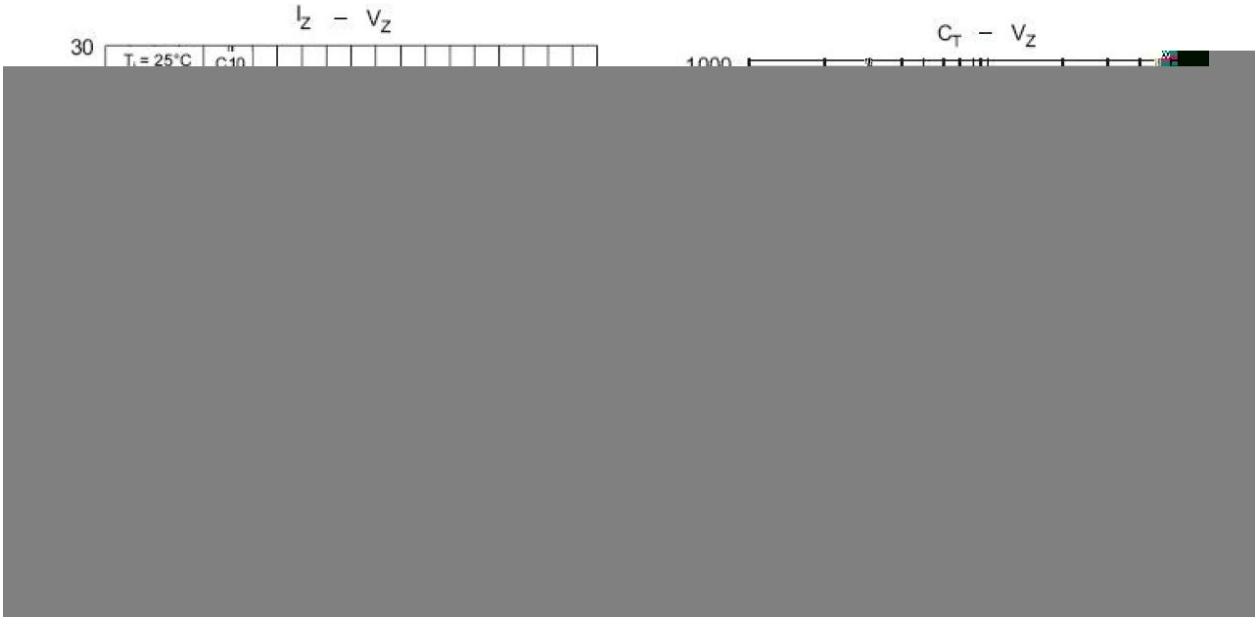
Parameter	Symbol	Rating	Unit
Forward Voltage(I_F=10mA)	V_F	0.9	V

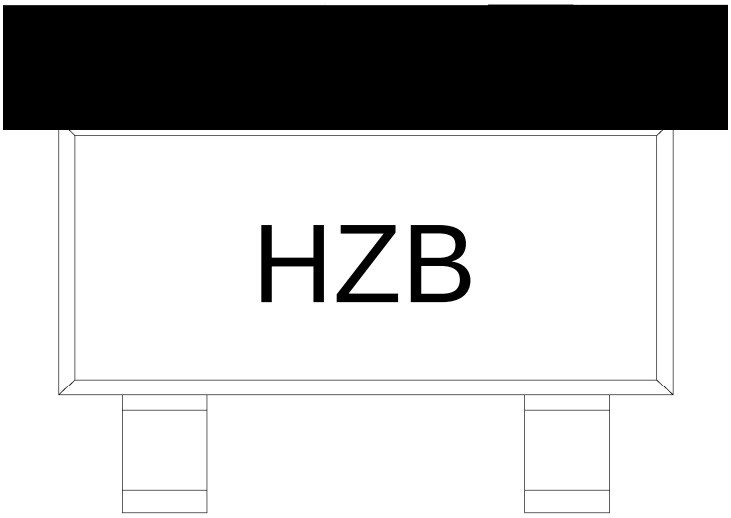
Type Number	Marking Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I_{ZT} mV/ºC	
		V_z @I_{ZT}			I_{ZT}	Z_{ZT} @I_{ZT}	Z_{ZK} @I_{ZK}		I_R	V_R		
		Nom (V)	Min (V)	Max (V)	mA	Ω	Ω	mA	uA	V	Min	Max
BZX84C18	HY6	18	16.8	19.1	5.0	45	225	1.0	0.1	12.6	12.4	16.0
BZX84C20	HY7	20	18.8	21.2	5.0	55	225	1.0	0.1	14.0	14.4	18.0
BZX84C22	HY8	22	20.8	23.3	5.0	55	250	1.0	0.1	15.4	16.4	20.0
BZX84C24	HY9	24	22.8	25.6	5.0	70	250	1.0	0.1	16.8	18.4	22.0
BZX84C27	HYA	27	25.1	28.9	2.0	80	300	0.5	0.1	18.9	21.4	25.3
BZX84C30	HYB	30	28.0	32.0	2.0	80	300	0.5	0.1	21.0	24.4	29.4
BZX84C33	HYC	33	31.0	35.0	2.0	80	325	0.5	0.1	23.1	27.4	33.4
BZX84C36	HYD	36	34.0	38.0	2.0	90	350	0.5	0.1	25.2	30.4	37.4
BZX84C39												

/ Electrical Characteristic Curve





/ Marking Instructions

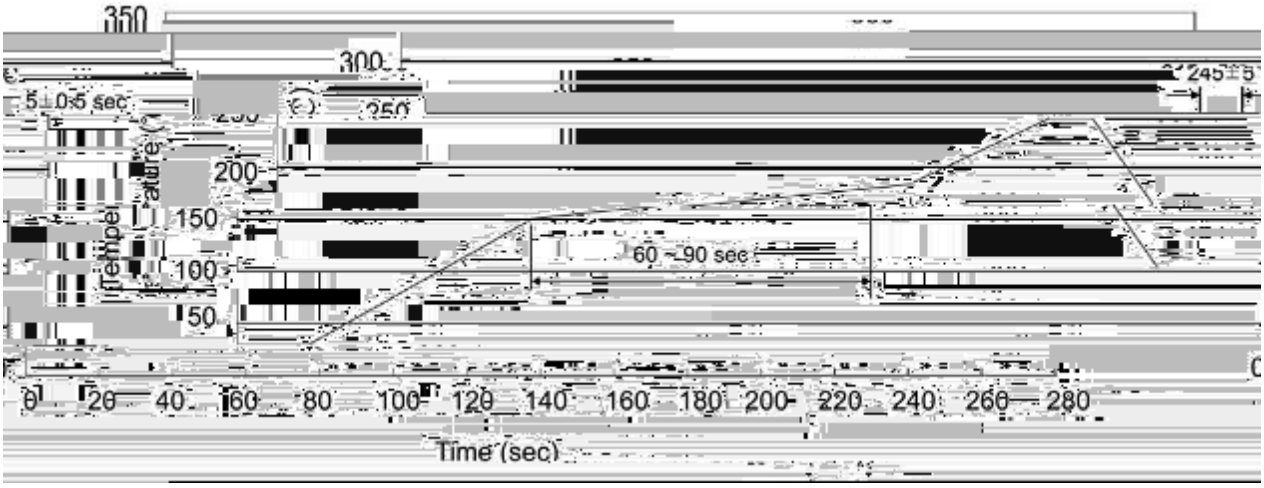


Note:

H: Company Code.

ZB: Product Type.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



			Note:
1	150 180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type !	Units " # $					Dimension " % & (unit ' mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box (	Outer Box)
SOT-23	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

/ Notices